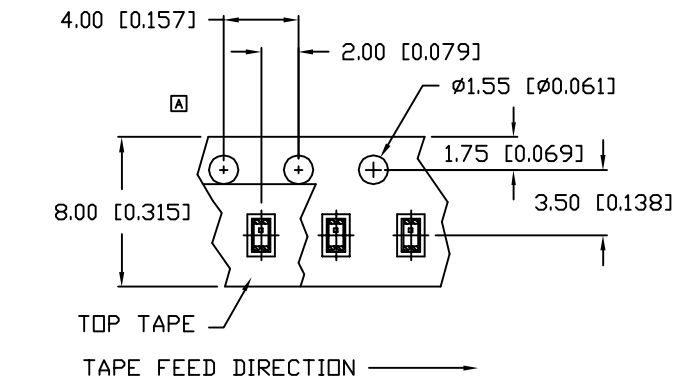
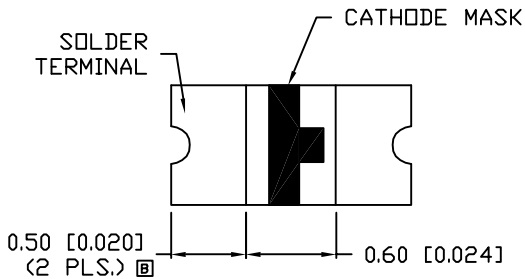
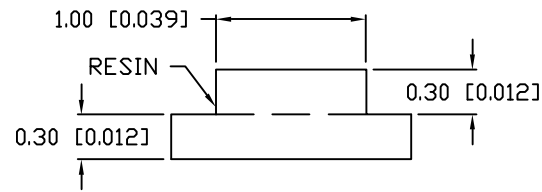
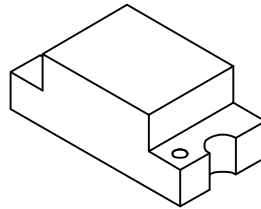
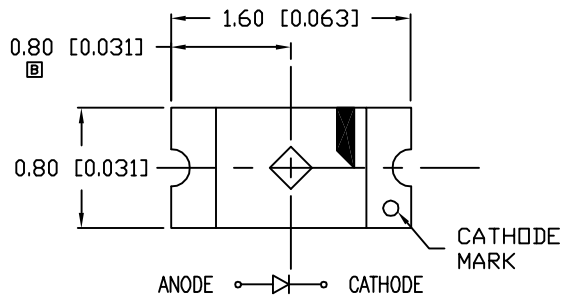
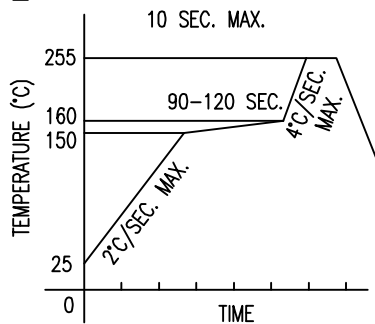


UNCONTROLLED DOCUMENT

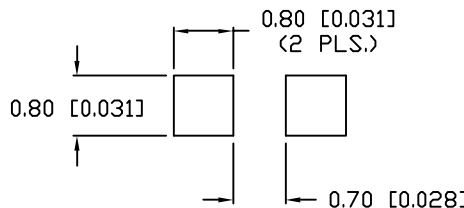


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER		REV.
SML-LX0603SGW-TR		E
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10644.	7.18.00
B	E.C.N. #10933.	12.3.02
C	E.C.N. #10967.	3.14.03
D	E.C.N. #11148.	12.06.04
E	E.C.N. #11508.	03.05.09

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100μA
AXIAL INTENSITY		20		mcd	I _f =20mA
VIEWING ANGLE		160		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	50	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-25 TO +85	°C
STORAGE TEMP.	-30 TO +85	°C

* t < 10μs

NOTES:

1. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 2 STANDARDS



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV.	PART NUMBER
E	SML-LX0603SGW-TR

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1.6mm x 0.8mm PCB CHIP, SURFACE MOUNT LED,
565nm SUPER GREEN LED, MILKY WHITE DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
CT			6.14.99
			PAGE: 1 OF 1
			SCALE: N/A